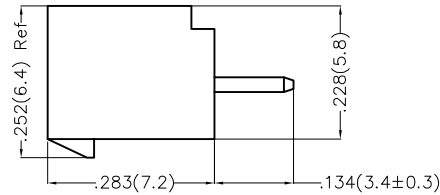
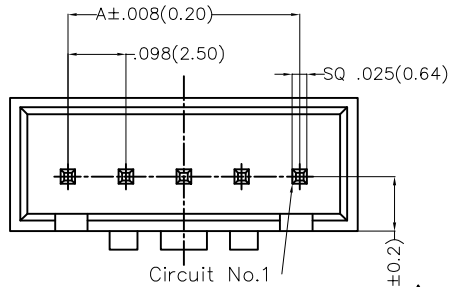


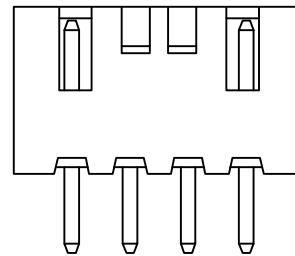
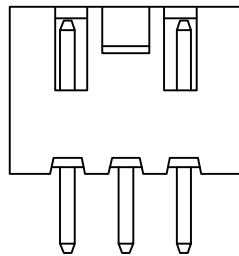
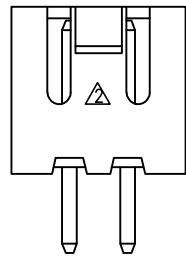
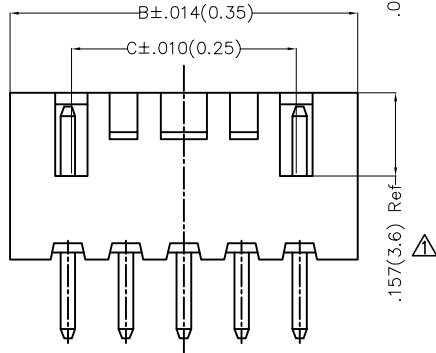
1 2 3 4 5 6 7 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	△	Dimensional tolerance change	21/JUL/23	MATT	LEO
2	△	1:Update the structure of 2Circuits 2:Update dimensions and tolerances 3:Increase the value of "C"	14/DEC/23	MATT	LEO



Electrical

Current Rating: 3.0A AC(rms)/DC
 Voltage Rating: 250V AC(rms)/DC
 Contact Resistance: 20 mΩ Max
 Insulation Resistance: 1000 MΩ MIN
 Withstanding Voltage: 1000V AC r.m.s
 Temperature Range—Operating: -25°C~+85°C
Material and Plating
 Housing: PA66(UL 94V-0)
 Contact Pin: Brass
 Plating: Tin Plated
 Mates With(Housing): FHG25006 Series



5-13Circuits

2Circuits

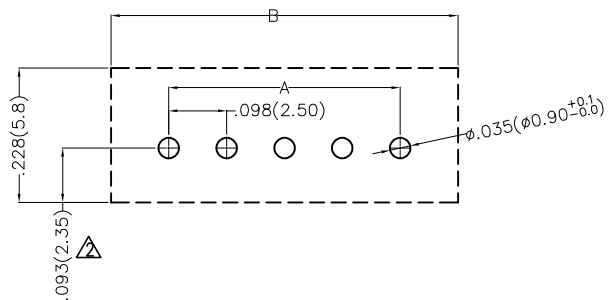
3Circuits

4Circuits

Ordering Information

FWF 250 12 — S XX S 2 2 XX B
 1 2 3 4 5 6 7 8 9 10

1 Category FWF—Wafer	2 Series Number 250—Pitch 2.5mm	3 Distinction No. 12	4 Row Option S—Single Row	5 Circuits XX	6 Entry Angle S—180° Vertical
7 Plating 2—Tin Plated	8 Material—Resin 2—PA66	9 Color—Resin W1—White R1—Red K6—Black N1—Green U1—Blue ...	10 Packaging B—PE Bag		



Recommended P.C.Board Layout

<p>THIRD ANGLE PROJECTION</p>	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/MAY/14	PART NO. FWF25012—SXXS22XXB	ITEM NO. FWF25012	<p>Building Technology Cornerstone</p>
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X:±5' .X'±2' .XX'±1' .XXX'±0.5'	CHECKED BY CHERRY	DATE 01/MAY/14	TITLE Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (DIP)	
SCALE 5:1	SIZE A4		DRAWN BY JACOB	DATE 01/MAY/14	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

1 2 3 4 5 6 7 8

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

A

A

B

B

C

C

D

D

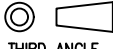

E

E

F

F

Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C Δ
2	FWF25012-S02S22W1B	.098(2.50)	.295(7.50)	.134(3.40)
3	FWF25012-S03S22W1B	.197(5.00)	.394(10.00)	.185(4.70)
4	FWF25012-S04S22W1B	.295(7.50)	.492(12.50)	.283(7.20)
5	FWF25012-S05S22W1B	.394(10.00)	.591(15.00)	.382(9.70)
6	FWF25012-S06S22W1B	.492(12.50)	.689(17.50)	.480(12.20)
7	FWF25012-S07S22W1B	.591(15.00)	.787(20.00)	.579(14.70)
8	FWF25012-S08S22W1B	.689(17.50)	.886(22.50)	.677(17.20)
9	FWF25012-S09S22W1B	.787(20.00)	.984(25.00)	.776(19.70)
10	FWF25012-S10S22W1B	.886(22.50)	1.083(27.50)	.874(22.20)
11	FWF25012-S11S22W1B	.984(25.00)	1.181(30.00)	.972(24.70)
12	FWF25012-S12S22W1B	1.083(27.50)	1.024(32.50)	1.071(27.20)
13	FWF25012-S13S22W1B	1.181(30.00)	1.378(35.00)	1.169(29.70)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/MAY/14	PART NO. FWF25012-SXXS22XXB	ITEM NO. FWF25012	 Building Technology Cornerstone	
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20) X.XX±.006(0.15) X.XXX±.004(0.10)	X.±5' .X'±2' .XX'±1' .XXX'±0.5'	CHECKED BY CHERRY	DATE 01/MAY/14	TITLE Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (DIP)		REV 2
SCALE 5:1	SIZE A4	DRAWN BY JACOB		DATE 01/MAY/14	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

1 | 2 | 3 | 4 | 5 | 6 | 7 | 8